

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

VOLTAGE RANGE

150 to 200 Volts

CURRENT

3.0 Amperes


SMC

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.21 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
 Single phase half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

P/N(MARK)	SS315C	SS320C	UNITS
Maximum Recurrent Peak Reverse Voltage	150	200	V
Maximum RMS Voltage	105	140	V
Maximum DC Blocking Voltage	150	200	V
Maximum Average Forward Rectified Current at T _L =100°C	3.0		A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	80		A
Maximum Instantaneous Forward Voltage at 3.0A	0.92		V
Maximum DC Reverse Current Ta=25°C	0.02		mA
at Rated DC Blocking Voltage Ta=100°C	2		mA
Typical Junction Capacitance (Note1)	250		PF
Typical Thermal Resistance R _θ JL (Note 2)	10		°C/W
Operating Temperature Range T _J	-65 — +175		°C
Storage Temperature Range T _{STG}	-65 — +175		°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead Vertical PC Board Mounting 0.5"(12.7mm) Lead Length.

RATING AND CHARACTERISTIC CURVES (SS315C THRU SS320C)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

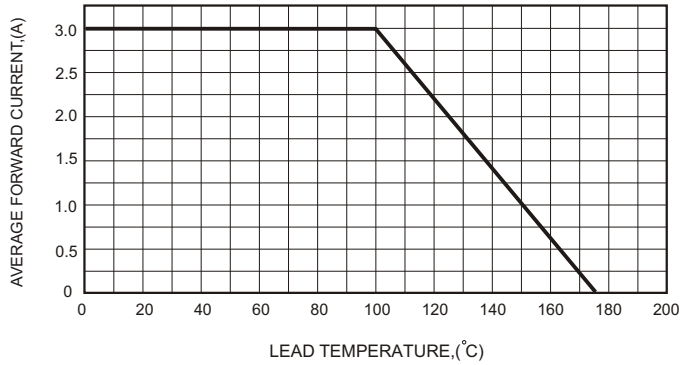


FIG.2-TYPICAL FORWARD CHARACTERISTICS

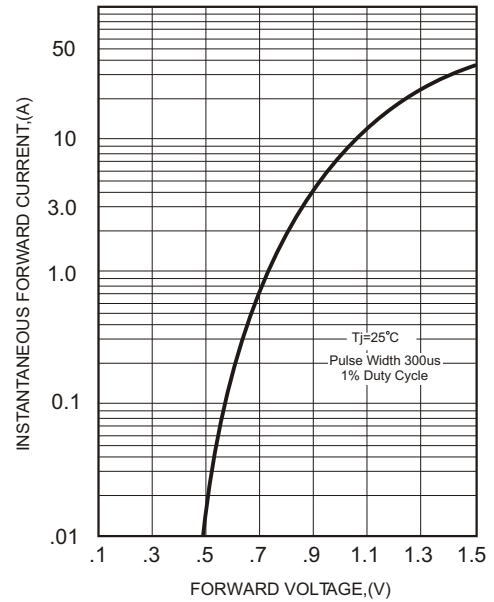


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

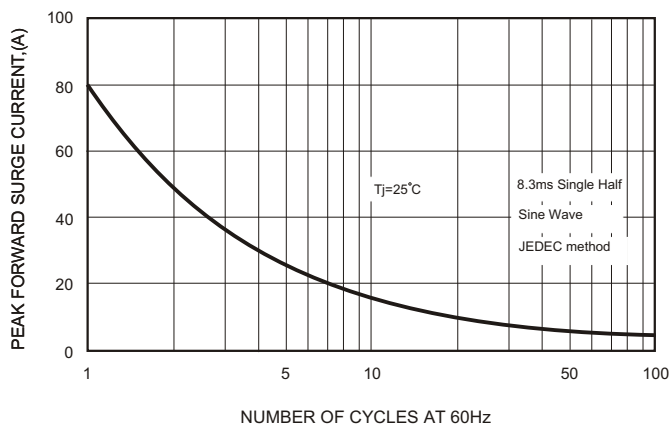


FIG.4-TYPICAL JUNCTION CAPACITANCE

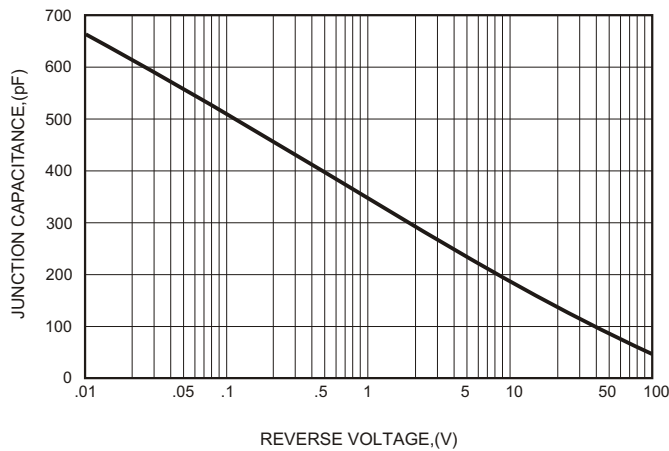
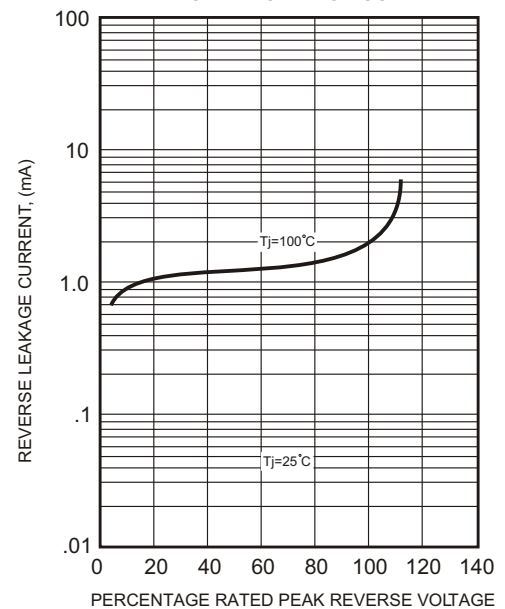
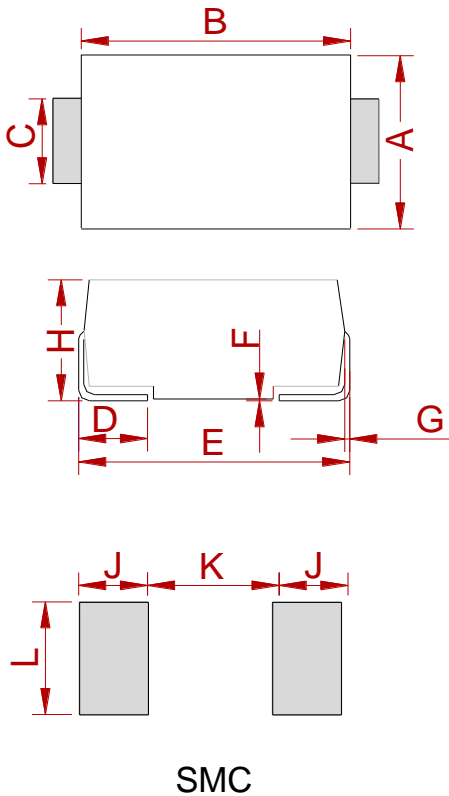


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	5.75	6.25	0.226	0.246
B	6.90	7.40	0.272	0.291
C	2.75	3.25	0.108	0.128
D	0.95	1.52	0.037	0.060
E	7.70	8.20	0.303	0.323
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.15	2.62	0.085	0.103
J	2.40		0.094	
K		4.20		0.165
L	3.30		0.130	

REEL SPECIFICATION

P/N	PKG	QTY
SS315C THRU SS320C	SMC	3000

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